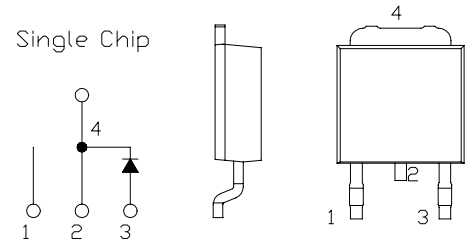


SBD Type : EA20QS04-F

OUTLINE DRAWING

FEATURES

- * TO-252AA Case, Surface Mounting Device
- * Low Forward Voltage drop
- * Low Power Loss
- * High Surge Capability
- * 40 Volts thru 100 Volts Types Available
- * Packaged in 16mm Tape and Reel



Maximum Ratings

Approx Net Weight:0.30g

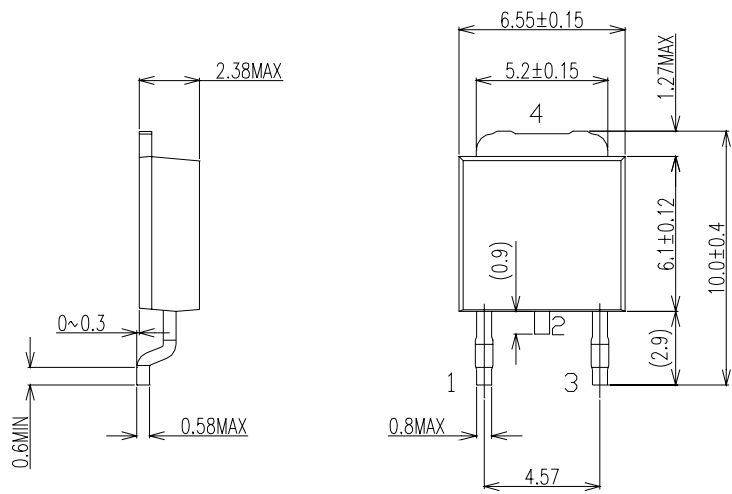
Rating		Symbol	EA20QS04-F			Unit
Repetitive Peak Reverse Voltage		V _{RRM}	40			V
Non-repetitive Peak Reverse Voltage		V _{RSM}	45			V
Average Rectified Output Current	P.C.Board mounted *	I _O	1.7	Ta=31°C	50Hz Half Sine Wave Resistive Load	A
	-		1.7	Tc=138°C		
RMS Forward Current		I _{F(RMS)}	2.67			A
Surge Forward Current		I _{FSM}	40	50Hz Half Sine Wave,1cycle, Non-repetitive		A
Operating JunctionTemperature Range		T _{jw}	- 40 to + 150			°C
Storage Temperature Range		T _{stg}	- 40 to + 150			°C

Electrical • Thermal Characteristics

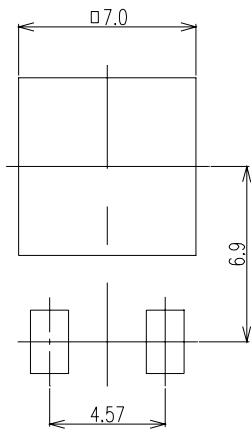
Characteristics		Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current		I_{RM}	$T_j=25^{\circ}\text{C}, V_{RM}=V_{RRM}$	-	-	2.0	mA
Peak Forward Voltage		V_{FM}	$T_j=25^{\circ}\text{C}, I_{FM}= 2 \text{ A}$	-	-	0.55	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	P.C.Board mounted *	-	-	80	$^{\circ}\text{C/W}$
	Junction to Case	$R_{th(j-c)}$	-	-	-	7	$^{\circ}\text{C/W}$

* Print Land = 20x20 mm

EA20QS04-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



Single Chip

